

Please amend claim 2 as follows:

1 2. (Amended) A flexible wiring board
 2 comprising:

 3 an insulating film having at least one
 4 principal surface;

 5 a [principal] printed conductive circuit layer
 6 formed at specified areas on said at least one principal
 7 surface of said insulating film,

 8 a metallic layer formed on the printed
 9 conductive circuit layer, said metallic layer having
 10 lands;

 11 an insulating layer formed on said metallic
 12 layer said insulating having openings exposing said
 13 lands, and

 14 a copper laminated polyimide board disposed in
 15 connection with said lands for soldering.

Please amend claim 3 as follows:

1 3. (Amended) A flexible wiring board
 2 comprising:

 3 an insulating [surface] film having a curved
 4 portion and at least one principal surface;

5 a printed conductive circuit layer formed at
6 specified areas on said at least one principal surface of
7 said insulating film,

8 a first insulating layer formed on at least the
9 [bent area]curved portion of said insulating film covered
10 by said printed conductive circuit layer,

11 a metallic layer formed on said printed
12 conductive circuit layer, and

13 a second insulating layer formed on specified
14 areas of said metallic layer.

[Please amend claim 4 as follows:]

[B1
Cont.
1 4. (Amended) A flexible wiring board
2 comprising:

3 an insulating film having at least one
4 principal surface[, said insulating film having at least
5 one bent area forming a cavity];

6 a printed conductive circuit layer formed at
7 specified areas on said at least one principal surface of
8 said insulating film said conductive circuit layer having
9 at least one cavity exposing said insulating film,

10 a metallic layer formed on said printed
11 conductive circuit layer, said metallic layer exposing
12 said cavity and having one or more connecting terminals,

13 an insulating layer formed on said metallic
14 layer, said insulating layer having openings exposing
15 said connecting terminals and said cavity, and
16 a reinforcement plate disposed [in said cavity
17 formed by] on a portion of a surface of said insulating
18 film.

Please amend claim 16 as follows:

1 ~~126.~~ (Amended) A flexible wiring board
2 comprising:

3 an insulating film having at least one
4 principal surface;

5 a first printed conductive circuit layer formed
6 at specified areas on said at least one principal surface
7 of said insulating film,

8 a first metallic layer formed on said first
9 printed conductive circuit layer, said metallic layer
10 having through-hole lands and external connecting
11 terminals;

12 [an] a first flexible insulating layer formed on
13 said insulating film and on said first metallic layer,
14 said insulating layer having holes exposing said through-
15 hole lands and exposing said external connecting
16 terminals;

17 a second printed conductive circuit layer
18 formed on said insulating layer in connection with said
19 through-hole lands, and

20 a second metallic layer formed on said second
21 printed conductive circuit layer.

Please amend claim 17 as follows:

1 ~~17.~~ (Amended) The flexible wiring board
2 according to Claim ~~16~~, which comprises:

3 a second insulating layer formed [on said
4 insulating layer and] on said [the] second metallic
5 layer, said second insulating layer having openings
6 exposing said through-hole lands and said external
connecting terminals,

8 a third printed conductive circuit layer formed
9 on said second insulating layer in connection with said
10 through-hole lands, and

11 a third metallic layer formed on said third
12 printed conductive circuit layer.

Please add new claim 30 as follows:

1 ~~14.~~ 30. (Newly added) A flexible wiring board
2 having:

3 an insulating film having at least one
4 principal surface;

5 a conductive circuit layer formed at specified
6 areas on said at least one principal surface;